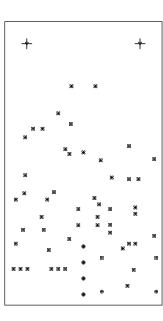


Layer	Name	Material	Thickness	Constant	Gerber	Board Layer Stack
	Top Overlay				GTO	
	Top Solder	Solder Resist	0.010mm	3.5	GTS	
1	Top Layer		0.035mm		GTL	
	Dielectric1	FR-4 (7628)	0.180mm	4.2		
	Dielectric 2	FR-4 (7628)	0.180mm	4.2		
2	MidLayer1		0.035mm		G1	
	Core		0.710mm	4.2		
3	MidLayer2		0.035mm		G2	
	Dielectric 3	FR-4 (7628)	0.180mm	4.2		
	Dielectric 4	FR-4 (7628)	0.180mm	4.2		
4	Bottom Layer		0.035mm		GBL	
	Bottom Solder	Solder Resist	0.010mm	3.5	GBS	
	Bottom Overlay				GBO	

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1.590mm





L	Symbol	Count	Hole Size	Hole Length	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
ſ	x	50	0.300mm (11.81mil)	-	РТН	Round	Top Layer - Bottom Layer	Via	Rounded
١		2	0.600mm (23.62mil)	1.600mm (62.99mil)	РТН	Slot	Top Layer - Bottom Layer	Pad	Rounded
١	0	2	0.600mm (23.62mil)	2.100mm (82.68mil)	РТН	Slot	Top Layer - Bottom Layer	Pad	Rounded
-	0	4	1.100mm (43.31mil)	-	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)
ı	∇	2	3.200mm (125.98mil)	-	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded
[60 Total							

